

HFA1130

850MHz, Output Limiting, Low Distortion Current Feedback Operational Amplifier

November 1996

Features

•	User Programmable Output Voltage Limits
•	Low Distortion (30MHz, HD2)56dBd
•	-3dB Bandwidth
•	Very Fast Slew Rate2300V/μs
•	Fast Settling Time (0.1%)
•	Excellent Gain Flatness
	- (100MHz)0.14dE
	- (50MHz) 0.04dB
	- (30MHz)
•	High Output Current60mA
•	Overdrive Recovery

Applications

- · Residue Amplifier
- · Video Switching and Routing
- Pulse and Video Amplifiers
- Wideband Amplifiers
- · RF/IF Signal Processing
- Flash A/D Driver
- Medical Imaging Systems
- · Related Literature
 - AN9420, Current Feedback Theory
 - AN9202, HFA11XX Evaluation Fixture

Description

The HFA1130 is a high speed wideband current feedback amplifier featuring programmable output limits. Built with Harris' proprietary complementary bipolar UHF-1 process, it is the fastest monolithic amplifier available from any semi-conductor manufacturer.

This amplifier is the ideal choice for high frequency applications requiring output limiting, especially those needing ultra fast overdrive recovery times. The output limiting function allows the designer to set the maximum positive and negative output levels, thereby protecting later stages from damage or input saturation. The sub-nanosecond overdrive recovery time quickly returns the amplifier to linear operation, following an overdrive condition.

The HFA1130 offers significant performance improvements over the CLC500/501/502.

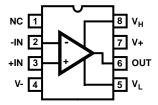
A variety of packages and temperature grades are available. See the ordering information below for details. For /883 product refer to the HFA1130/883 datasheet.

Ordering Information

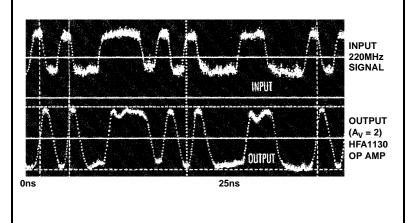
PART NUMBER (BRAND)	TEMP. RANGE (°C)	PACKAGE	PKG. NO.	
HFA1130MJ/883	-55 to 125	8 Ld CERDIP	F8.3A	
HFA1130IJ	-40 to 85	8 Ld CERDIP	F8.3A	
HFA1130IP	-40 to 85	8 Ld PDIP	E8.3	
HFA1130IB (H1130I)			M8.15	
HFA11XXEVAL	AL DIP Evaluation Board for High-Speed C			

Pinout

HFA1130 (PDIP, CERDIP, SOIC) TOP VIEW



The Op Amps With Fastest Edges



HFA1130

Absolute Maximum Ratings $T_A = 25^{\circ}C$ **Thermal Information** Thermal Resistance (Typical, Note 1) θ_{JA} (°C/W) θ_{JC} (oC/W) CERDIP Package Input Voltage..... V_{SUPPLY} 120 35 Differential Input Voltage. 5V 130 N/A 170 N/A Maximum Junction Temperature (Die or CERDIP) 175°C Maximum Junction Temperature (Plastic Package) 150°C **Operating Conditions** Maximum Storage Temperature Range -65°C to T_A to 150°C Temperature Range -40°C to 85°C Maximum Lead Temperature (Soldering 10s).....300°C (SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. θ_{JA} is measured with the component mounted on an evaluation PC board in free air.

Electrical Specifications $V_{SUPPLY} = \pm 5V$, $A_V = +1$, $R_F = 510\Omega$, $R_L = 100\Omega$, Unless Otherwise Specified

PARAMETER	TEST CONDITIONS	(NOTE 2) TEST LEVEL	TEMP.	MIN	TYP	MAX	UNITS
INPUT CHARACTERISTICS	INPUT CHARACTERISTICS						
Input Offset Voltage (Note 3)		А	25	-	2	6	mV
		Α	Full	-	-	10	mV
Input Offset Voltage Drift		С	Full	-	10	-	μV/°C
V _{IO} CMRR	$\Delta V_{CM} = \pm 2V$	Α	25	40	46	-	dB
		Α	Full	38	-	-	dB
V _{IO} PSRR	$\Delta V_S = \pm 1.25 V$	А	25	45	50	-	dB
		А	Full	42	-	-	dB
Non-Inverting Input Bias Current	+IN = 0V	А	25	-	25	40	μΑ
(Note 3)		Α	Full	-	-	65	μΑ
+I _{BIAS} Drift		С	Full	-	40	-	nA/°C
+I _{BIAS} CMS	$\Delta V_{CM} = \pm 2V$	Α	25	-	20	40	μA/V
		Α	Full	-	-	50	μA/V
Inverting Input Bias Current (Note 3)	-IN = 0V	Α	25	-	12	50	μΑ
		А	Full	-	-	60	μΑ
-I _{BIAS} Drift		С	Full	-	40	-	nA/°C
-I _{BIAS} CMS	$\Delta V_{CM} = \pm 2V$	А	25	-	1	7	μΑ/V
		А	Full	-	-	10	μΑ/V
-I _{BIAS} PSS	$\Delta V_S = \pm 1.25V$	А	25	-	6	15	μA/V
		А	Full	-	-	27	μΑ/V
Non-Inverting Input Resistance		А	25	25	50	-	kΩ
Inverting Input Resistance		С	25	-	20	30	Ω
Input Capacitance (Either Input)		В	25	-	2	-	pF
Input Common Mode Range		С	Full	±2.5	±3.0	-	V
Input Noise Voltage (Note 3)	100kHz	В	25	-	4	-	nV/√ Hz
+Input Noise Current (Note 3)	100kHz	В	25	-	18	-	pA/√ Hz
-Input Noise Current (Note 3)	100kHz	В	25	-	21	-	pA/√ Hz
TRANSFER CHARACTERISTICS A	/ = +2, Unless Otherwis	se Specified			-	-	-
Open Loop Transimpedance (Note 3)		В	25	-	300	-	kΩ
-3dB Bandwidth (Note 3)	$V_{OUT} = 0.2V_{P-P},$ $A_V = +1$	В	25	530	850	-	MHz

 $\textbf{Electrical Specifications} \qquad \text{V_{SUPPLY} = ± 5V, A_V = $+1$, R_F = 510\Omega$, R_L = 100\Omega$, Unless Otherwise Specified$ **(Continued)** $}$

PARAMETER	TEST CONDITIONS	(NOTE 2) TEST LEVEL	TEMP. (°C)	MIN	ТҮР	MAX	UNITS
-3dB Bandwidth	$V_{OUT} = 0.2V_{P-P},$ $A_V = +2, R_F = 360\Omega$	В	25	-	670	-	MHz
Full Power Bandwidth	$4V_{P-P}, A_V = -1$	В	Full	-	300	-	MHz
Gain Flatness (Note 3)	To 100MHz	В	25	-	±0.14	-	dB
Gain Flatness	To 50MHz	В	25	-	±0.04	-	dB
Gain Flatness	To 30MHz	В	25	-	±0.01	=	dB
Linear Phase Deviation (Note 3)	DC to 100MHz	В	25	-	0.6	=	Degrees
Differential Gain	NTSC, $R_L = 75\Omega$	В	25	-	0.03	-	%
Differential Phase	NTSC, $R_L = 75\Omega$	В	25	-	0.05	-	Degrees
Minimum Stable Gain		Α	Full	1	-	=	V/V
OUTPUT CHARACTERISTICS A _V =	+2, Unless Otherwise S	pecified					
Output Voltage (Note 3)	A _V = -1	Α	25	±3.0	±3.3	-	V
		Α	Full	±2.5	±3.0	=	V
Output Current	$R_L = 50\Omega, A_V = -1$	Α	25, 85	50	60	=	mA
		Α	-40	35	50	=	mA
DC Closed Loop Output Impedance (Note 3)		В	25	-	0.07	-	Ω
2nd Harmonic Distortion (Note 3)	30MHz, $V_{OUT} = 2V_{P-P}$	В	25	-	-56	-	dBc
3rd Harmonic Distortion (Note 3)	30MHz, $V_{OUT} = 2V_{P-P}$	В	25	-	-80	-	dBc
3rd Order Intercept (Note 3)	100MHz	В	25	20	30	-	dBm
1dB Compression	100MHz	В	25	15	20	-	dBm
TRANSIENT RESPONSE A _V = +2, l	Jnless Otherwise Specifi	ed					•
Rise Time	V _{OUT} = 2.0V Step	В	25	-	900	-	ps
Overshoot (Note 3)	V _{OUT} = 2.0V Step	В	25	-	10	-	%
Slew Rate	$A_{V} = +1,$ $V_{OUT} = 5V_{P-P}$	В	25	-	1400	-	V/µs
	$A_V = +2,$ $V_{OUT} = 5V_{P-P}$	В	25	1850	2300	-	V/µs
0.1% Settling Time (Note 3)	V _{OUT} = 2V to 0V	В	25	-	11	-	ns
0.2% Settling Time (Note 3)	V _{OUT} = 2V to 0V	В	25	-	7	-	ns
POWER SUPPLY CHARACTERISTIC	CS .						
Supply Voltage Range		В	Full	±4.5	-	±5.5	V
Supply Current (Note 3)		А	25	-	21	26	mA
		А	Full	-	-	33	mA
LIMITING CHARACTERISTICS A _V	= +2, V _H = +1V, V _L = -1V	, Unless Ot	herwise S	pecified			•
Clamp Accuracy	$V_{1N} = \pm 2V, A_V = -1$	Α	25	-	60	±125	mV
Clamped Overshoot	$V_{IN} = \pm 1V$, Input $t_R/t_F = 2ns$	В	25	-	4	-	%
Overdrive Recovery Time	V _{IN} = ±1V	В	25	-	0.75	1.5	ns
Negative Clamp Range		В	25	-	-5.0 to +2.0	-	V
Positive Clamp Range		В	25	-	-2.0 to +5.0	-	V
Clamp Input Bias Current		А	25	-	50	200	μΑ
Clamp Input Bandwidth	V_H or $V_L = 100 \text{mV}_{P-P}$	В	25	-	500	-	MHz

NOTES:

- 2. Test Level: A. Production Tested; B. Typical or Guaranteed Limit Based on Characterization; C. Design Typical for Information Only.
- 3. See Typical Performance Curves for more information.

Application Information

Optimum Feedback Resistor (R_F)

The enclosed plots of inverting and non-inverting frequency response detail the performance of the HFA1100/1120 in various gains. Although the bandwidth dependency on A_{CL} isn't as severe as that of a voltage feedback amplifier, there is an appreciable decrease in bandwidth at higher gains. This decrease can be minimized by taking advantage of the current feedback amplifier's unique relationship between bandwidth and R_F. All current feedback amplifiers require a feedback resistor, even for unity gain applications, and the R_E, in conjunction with the internal compensation capacitor, sets the dominant pole of the frequency response. Thus, the amplifier's bandwidth is inversely proportional to R_F. The HFA1100, 1120 designs are optimized for a 510 Ω R_F, at a gain of +1. Decreasing R_F in a unity gain application decreases stability, resulting in excessive peaking and overshoot (Note: Capacitive feedback causes the same problems due to the feedback impedance decrease at higher frequencies). At higher gains the amplifier is more stable, so R_F can be decreased in a trade-off of stability for bandwidth. The table below lists recommended R_F values for various gains, and the expected bandwidth.

A _{CL}	R _F (Ω)	BW (MHz)			
+1	510	850			
-1	430	580			
+2	360	670			
+5	150	520			
+10	180	240			
+19	270	125			

Clamp Operation

General

The HFA1130 features user programmable output clamps to limit output voltage excursions. Clamping action is obtained by applying voltages to the V_H and V_L terminals (pins 8 and 5) of the amplifier. V_H sets the upper output limit, while V_L sets the lower clamp level. If the amplifier tries to drive the output above V_H , or below V_L , the clamp circuitry limits the output voltage at V_H or V_L (\pm the clamp accuracy), respectively. The low input bias currents of the clamp pins allow them to be driven by simple resistive divider circuits, or active elements such as amplifiers or DACs.

Clamp Circuitry

Figure 1 shows a simplified schematic of the HFA1130 input stage, and the high clamp (V_H) circuitry. As with all current feedback amplifiers, there is a unity gain buffer (Q_{X1} - Q_{X2}) between the positive and negative inputs. This buffer forces -IN to track +IN, and sets up a slewing current of (V_{IN} - V_{OUT})/ R_F . This current is mirrored onto the high impedance node (Z) by Q_{X3} - Q_{X4} , where it is converted to a voltage and fed to the output via another unity gain buffer. If no clamping is utilized, the high impedance node may swing within the limits defined by Q_{P4} and Q_{N4} . Note that when the output reaches it's quiescent value, the current flowing through -IN is reduced to only that small current (- I_{RIAS}) required to keep the output at the final voltage.

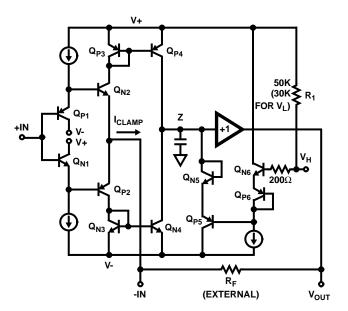


FIGURE 1. HFA1130 SIMPLIFIED VH CLAMP CIRCUITRY

Tracing the path from V $_{\rm H}$ to Z illustrates the effect of the clamp voltage on the high impedance node. V $_{\rm H}$ decreases by 2V $_{\rm BE}$ (Q $_{\rm N6}$ and Q $_{\rm P6}$) to set up the base voltage on Q $_{\rm P5}$. Q $_{\rm P5}$ begins to conduct whenever the high impedance node reaches a voltage equal to Q $_{\rm P5}$'s base + 2V $_{\rm BE}$ (Q $_{\rm P5}$ and Q $_{\rm N5}$). Thus, Q $_{\rm P5}$ clamps node Z whenever Z reaches V $_{\rm H}$. R $_{\rm 1}$ provides a pull-up network to ensure functionality with the clamp inputs floating. A similar description applies to the symmetrical low clamp circuitry controlled by V $_{\rm I}$.

When the output is clamped, the negative input continues to source a slewing current (I_{CLAMP}) in an attempt to force the output to the quiescent voltage defined by the input. Q_{P5} must sink this current while clamping, because the -IN current is always mirrored onto the high impedance node. The clamping current is calculated as (V_{-IN} - V_{OUT})/ R_F . As an example, a unity gain circuit with V_{IN} = 2V, V_H = 1V, and R_F = 510 Ω would have I_{CLAMP} = (2-1)/510 Ω = 1.96mA. Note that I_{CC} will increase by I_{CLAMP} when the output is clamp limited.

Clamp Accuracy

The clamped output voltage will not be exactly equal to the voltage applied to VH or VL. Offset errors, mostly due to VBE mismatches, necessitate a clamp accuracy parameter which is found in the device specifications. Clamp accuracy is a function of the clamping conditions. Referring again to Figure 1, it can be seen that one component of clamp accuracy is the VBE mismatch between the Q_{X6} transistors, and the Q_{X5} transistors. If the transistors always ran at the same current level there would be no V_{BE} mismatch, and no contribution to the inaccuracy. The Q_{X6} transistors are biased at a constant current, but as described earlier, the current through Q_{X5} is equivalent to I_{CLAMP}. V_{BE} increases as I_{CLAMP} increases, causing the clamped output voltage to increase as well. I_{CLAMP} is a function of the overdrive level (V-IN-VOUTCLAMPED) and R_F, so clamp accuracy degrades as the overdrive increases, or as RF decreases. As an example, the specified accuracy of ±60mV for a 2X overdrive with $R_F = 510\Omega$ degrades to ± 220 mV for $R_F = 240\Omega$ at the same overdrive, or to ± 250 mV for a 3X overdrive with $R_F = 510\Omega$.

Consideration must also be given to the fact that the clamp voltages have an effect on amplifier linearity. The "Nonlinearity Near Clamp Voltage" curve in the data sheet illustrates the impact of several clamp levels on linearity.

Clamp Range

Unlike some competitor devices, both V_H and V_L have usable ranges that cross 0V. While V_H must be more positive than V_L , both may be positive or negative, within the range restrictions indicated in the specifications. For example, the HFA1130 could be limited to ECL output levels by setting $V_H = -0.8V$ and $V_L = -1.8V$. V_H and V_L may be connected to the same voltage (GND for instance) but the result won't be in a DC output voltage from an AC input signal. A 150 - 200mV AC signal will still be present at the output.

Recovery from Overdrive

The output voltage remains at the clamp level as long as the overdrive condition remains. When the input voltage drops below the overdrive level (V_{CLAMP}/A_{VCL}) the amplifier will return to linear operation. A time delay, known as the Overdrive Recovery Time, is required for this resumption of linear operation. The plots of "Unclamped Performance" and "Clamped Performance" highlight the HFA1130's subnanosecond recovery time. The difference between the unclamped and clamped propagation delays is the overdrive recovery time. The appropriate propagation delays are 4.0ns for the unclamped pulse, and 4.8ns for the clamped (2X overdrive) pulse yielding an overdrive recovery time of 800ps. The measurement uses the 90% point of the output transition to ensure that linear operation has resumed. Note: The propagation delay illustrated is dominated by the fixturing. The delta shown is accurate, but the true HFA1130 propagation delay is 500ps.

Use of Die in Hybrid Applications

This amplifier is designed with compensation to negate the package parasitics that typically lead to instabilities. As a result, the use of die in hybrid applications results in overcompensated performance due to lower parasitic capacitances. Reducing R_{F} below the recommended values for packaged units will solve the problem. For A_{V} = +2 the recommended starting point is $300\Omega_{\rm h}$, while unity gain applications should try $400\Omega_{\rm h}$

PC Board Layout

The frequency performance of this amplifier depends a great deal on the amount of care taken in designing the PC board. The use of low inductance components such as chip resistors and chip capacitors is strongly recommended, while a solid ground plane is a must!

Attention should be given to decoupling the power supplies. A large value ($10\mu F$) tantalum in parallel with a small value chip ($0.1\mu F$) capacitor works well in most cases.

Terminated microstrip signal lines are recommended at the input and output of the device. Output capacitance, such as that resulting from an improperly terminated transmission line will degrade the frequency response of the amplifier and

may cause oscillations. In most cases, the oscillation can be avoided by placing a resistor in series with the output.

Care must also be taken to minimize the capacitance to ground seen by the amplifier's inverting input. The larger this capacitance, the worse the gain peaking, resulting in pulse overshoot and possible instability. To this end, it is recommended that the ground plane be removed under traces connected to pin 2, and connections to pin 2 should be kept as short as possible.

An example of a good high frequency layout is the Evaluation Board shown below.

Evaluation Board

An evaluation board is available for the HFA1130, (Part Number HFA11XXEVAL). Please contact your local sales office for information.

The layout and schematic of the board are shown here:

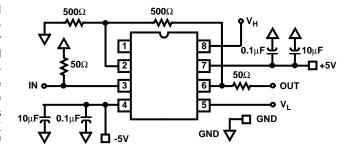
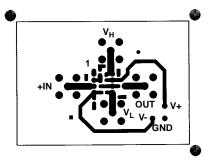
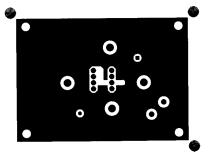


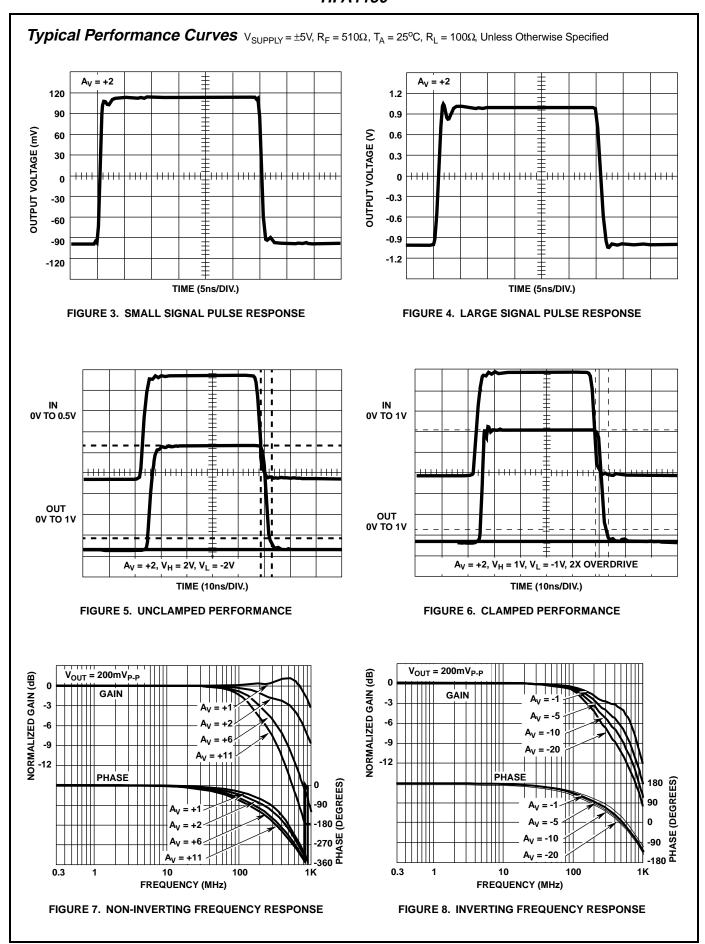
FIGURE 2. BOARD SCHEMATIC

TOP LAYOUT

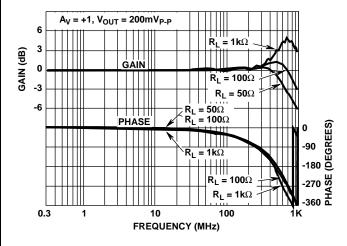


BOTTOM LAYOUT









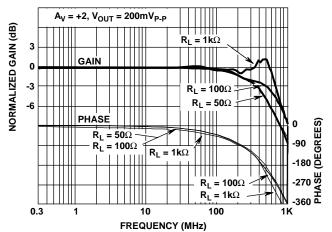
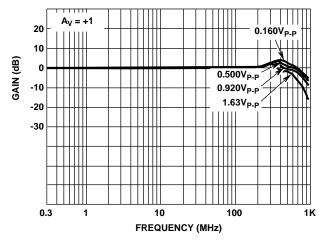


FIGURE 9. FREQUENCY RESPONSE FOR VARIOUS LOAD RESISTORS

FIGURE 10. FREQUENCY RESPONSE FOR VARIOUS LOAD RESISTORS



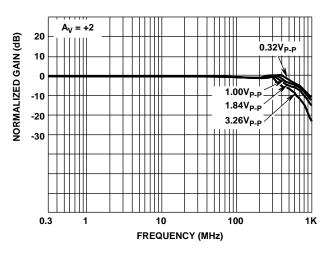
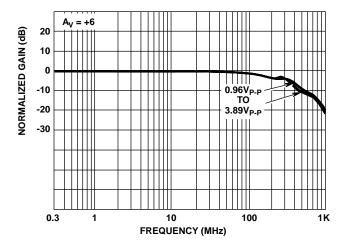


FIGURE 11. FREQUENCY RESPONSE FOR VARIOUS OUTPUT VOLTAGES

FIGURE 12. FREQUENCY RESPONSE FOR VARIOUS OUTPUT VOLTAGES



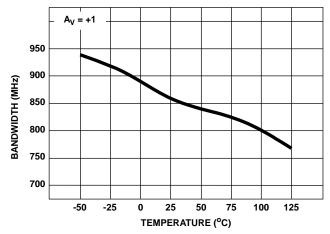
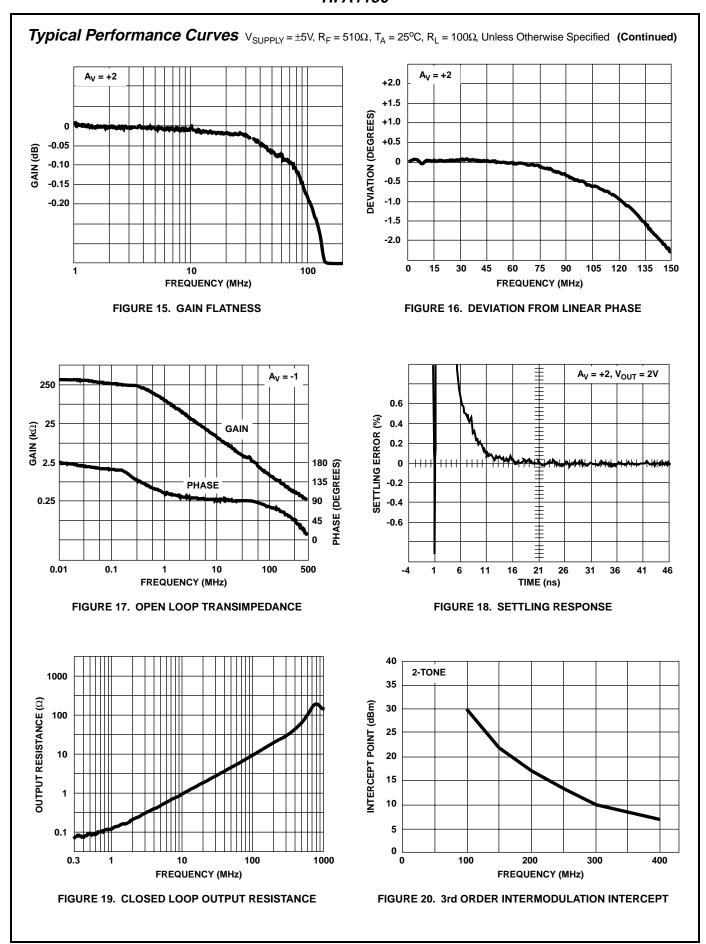
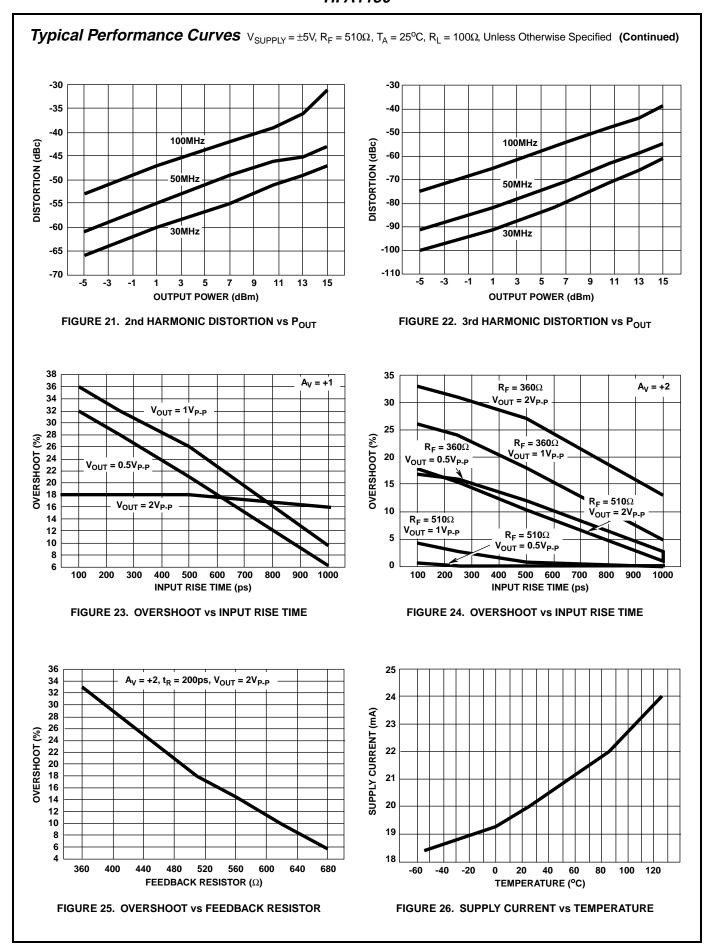


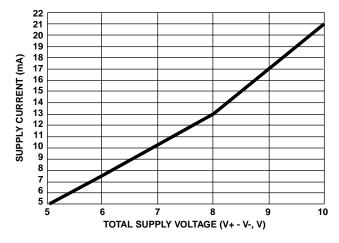
FIGURE 13. FREQUENCY RESPONSE FOR VARIOUS OUTPUT VOLTAGES

FIGURE 14. -3dB BANDWIDTH vs TEMPERATURE









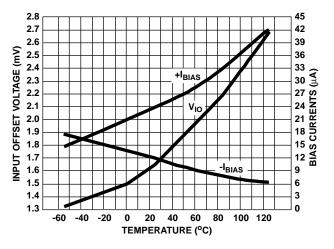
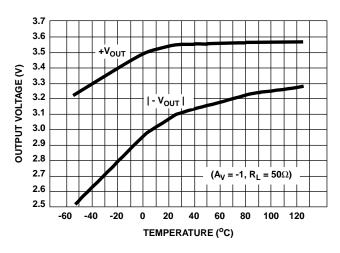


FIGURE 27. SUPPLY CURRENT vs SUPPLY VOLTAGE

FIGURE 28. V_{IO} and bias currents vs temperature



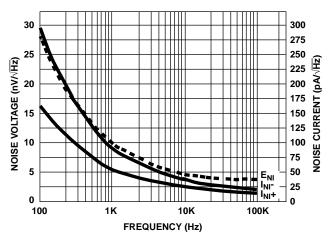


FIGURE 29. OUTPUT VOLTAGE vs TEMPERATURE

FIGURE 30. INPUT NOISE vs FREQUENCY

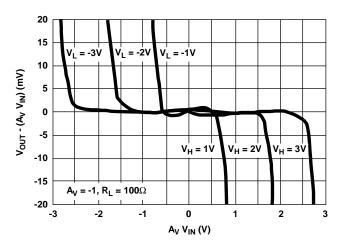


FIGURE 31. NON-LINEARITY NEAR CLAMP VOLTAGE

Die Characteristics

DIE DIMENSIONS:

63 mils x 44 mils x 19 mils 1600μm x 1130μm

METALLIZATION:

Type: Metal 1: AlCu(2%)/TiW Thickness: Metal 1: $8k\mathring{A} \pm 0.4k\mathring{A}$

Type: Metal 2: ALCu(2%)

Thickness: Metal 2: 16kÅ ±0.8kÅ

PASSIVATION:

Type: Nitride

Thickness: 4kÅ ±0.5kÅ

TRANSISTOR COUNT:

52

SUBSTRATE POTENTIAL (Powered Up):

Floating (Recommend Connection to V-)

Metallization Mask Layout

